
Chapter 1

Introduction

The Story Begins

Integration Scale	Number of Components	Examples
SSI	< 10 transistors	Logic gates
MSI	10 - 1,000 transistors	Adders, counters
LSI	1,000 - 10,000 transistors	Multipliers
VLSI	> 10,000 transistors	Microprocessors

Fig. 1.1 Integration scales.

Moore's Law

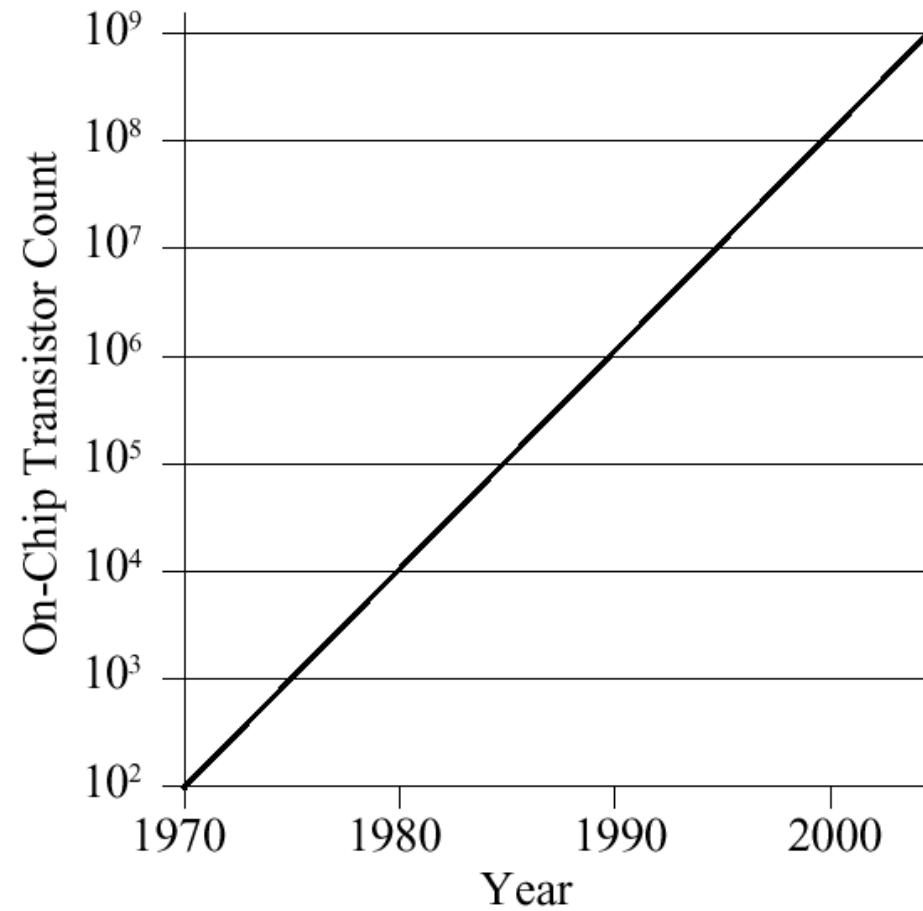


Fig. 1.2 Moore's law.

VLSI Design Methodology

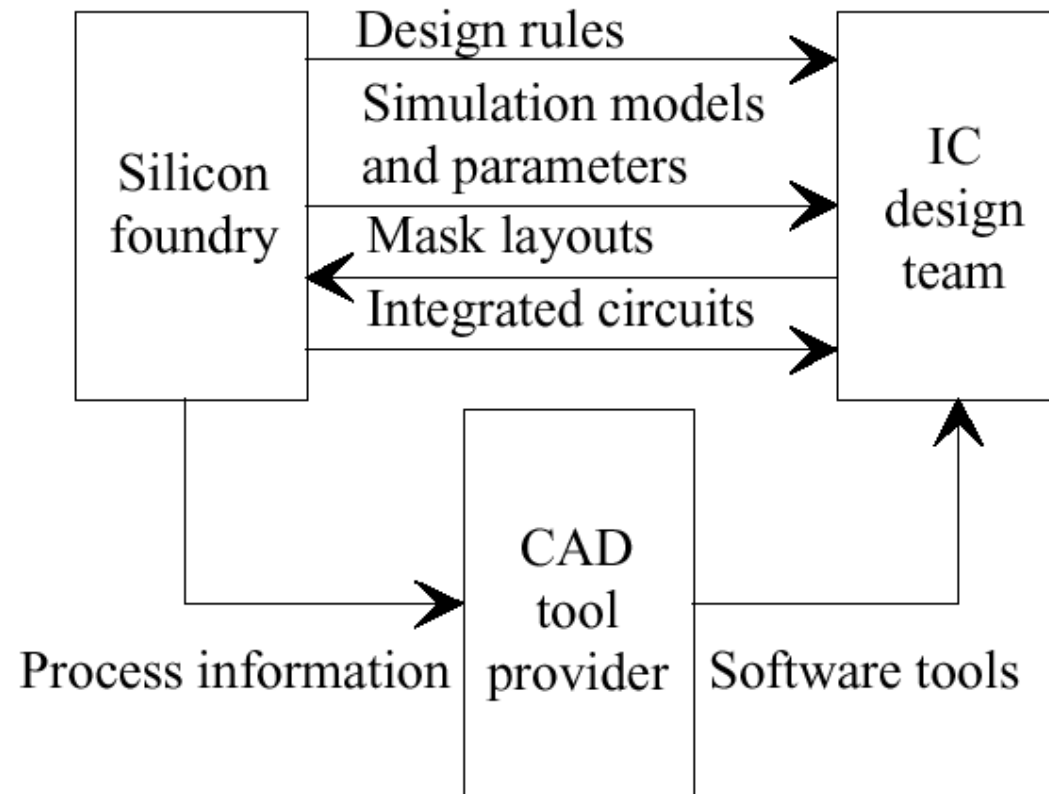


Fig. 1.3 Relationship between a silicon foundry, an IC design team, and a CAD tool provider.

Behavioral (Functional) Design

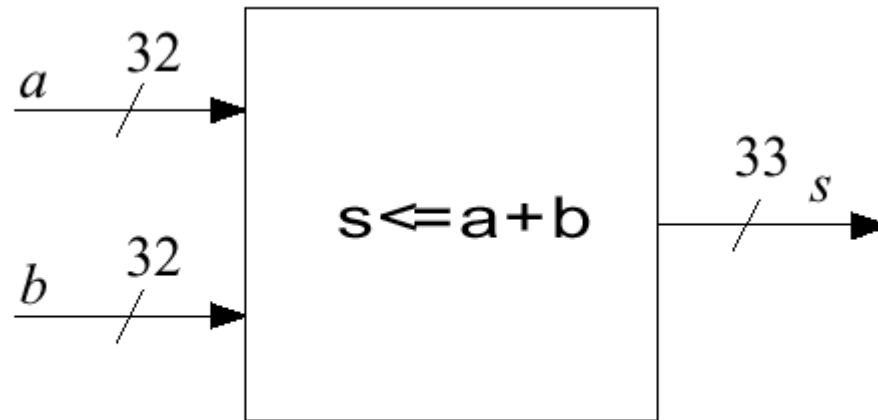


Fig. 1.4 Graphical behavioral representation of an adder.

Behavioral (Functional) Design

```
-- Interface
ENTITY adder IS
    PORT (a, b: IN unsigned(0 to 31);
          s: OUT unsigned(0 to 32));
END adder;

-- Behavioral representation
ARCHITECTURE behavioral OF adder IS
BEGIN
    s <= a + b;
END behavioral;
```

Structural (Architectural) Design

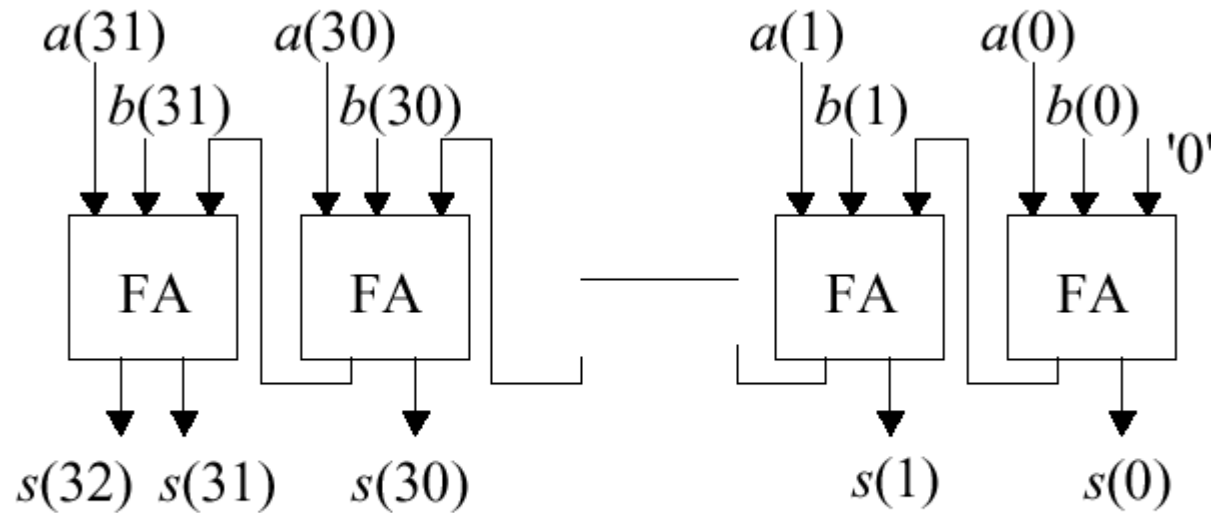


Fig. 1.5 Ripple-carry adder.

Logic Design

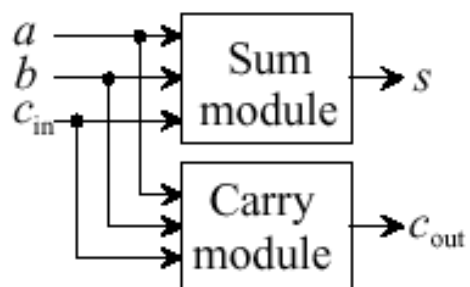


Fig. 1.6 I/O interface of a 1-bit full adder.

$$s = a \oplus b \oplus c_{in}$$

a	b	c_{in}	c_{out}
0	0	0	0
0	0	1	0
0	1	0	0
0	1	1	1
1	0	0	0
1	0	1	1
1	1	0	1
1	1	1	1

VHDL Design

```
-- Interface of a full adder (Part 1)
ENTITY full_adder IS
    PORT (a, b, cin: IN BIT; s, cout: OUT BIT);
END full_adder;

-- Behavioral representation of a full adder (Part 2)

ARCHITECTURE behavioral OF full_adder IS
    -- carry() and sum()
    FUNCTION carry(a, b, cin: BIT) RETURN BIT IS
    BEGIN
        RETURN (a AND b) OR (b AND cin) OR (a AND cin);
    END carry;
    FUNCTION sum(a, b, cin: BIT) RETURN BIT IS
    BEGIN
        RETURN a XOR b XOR cin;
    END sum;
    -- Relationship between the outputs and inputs
    -- with propagation delay information
    BEGIN
        s <= sum(a, b, cin) AFTER 1 ns;
        cout <= carry(a, b, cin) AFTER 0.8 ns;
    END behavioral;
```

VHDL Design

```
-- Structural representation of a full adder (Part 3)
ARCHITECTURE structural OF full_adder IS
-- Component list
COMPONENT xor_cell
    PORT (a, b: IN BIT; z: OUT BIT);
END COMPONENT;
COMPONENT or_cell
    PORT (a, b: IN BIT; z: OUT BIT);
END COMPONENT;
COMPONENT and_cell
    PORT (a, b: IN BIT; z: OUT BIT);
END COMPONENT;
```

VHDL Design

```
-- Sources of components
FOR ALL:xor_cell USE ENTITY WORK.lib_xor(structural);
FOR ALL:or_cell USE ENTITY WORK.lib_or(structural);
FOR ALL:and_cell USE ENTITY WORK.lib_and(structural);

-- Internal wires
SIGNAL wire1, wire2, wire3, wire4, wire5: BIT;

-- Connections
BEGIN
    a1: xor_cell PORT MAP(a, b, wire1);
    a2: xor_cell PORT MAP(wire1, cin, s);
    a3: and_cell PORT MAP(a, b, wire2);
    a4: and_cell PORT MAP(a, cin, wire3);
    a5: and_cell PORT MAP(b, cin, wire4);
    a6: or_cell PORT MAP(wire2, wire3, wire5);
    a7: or_cell PORT MAP(wire4, wire5, cout);
END structural
```

Physical Design

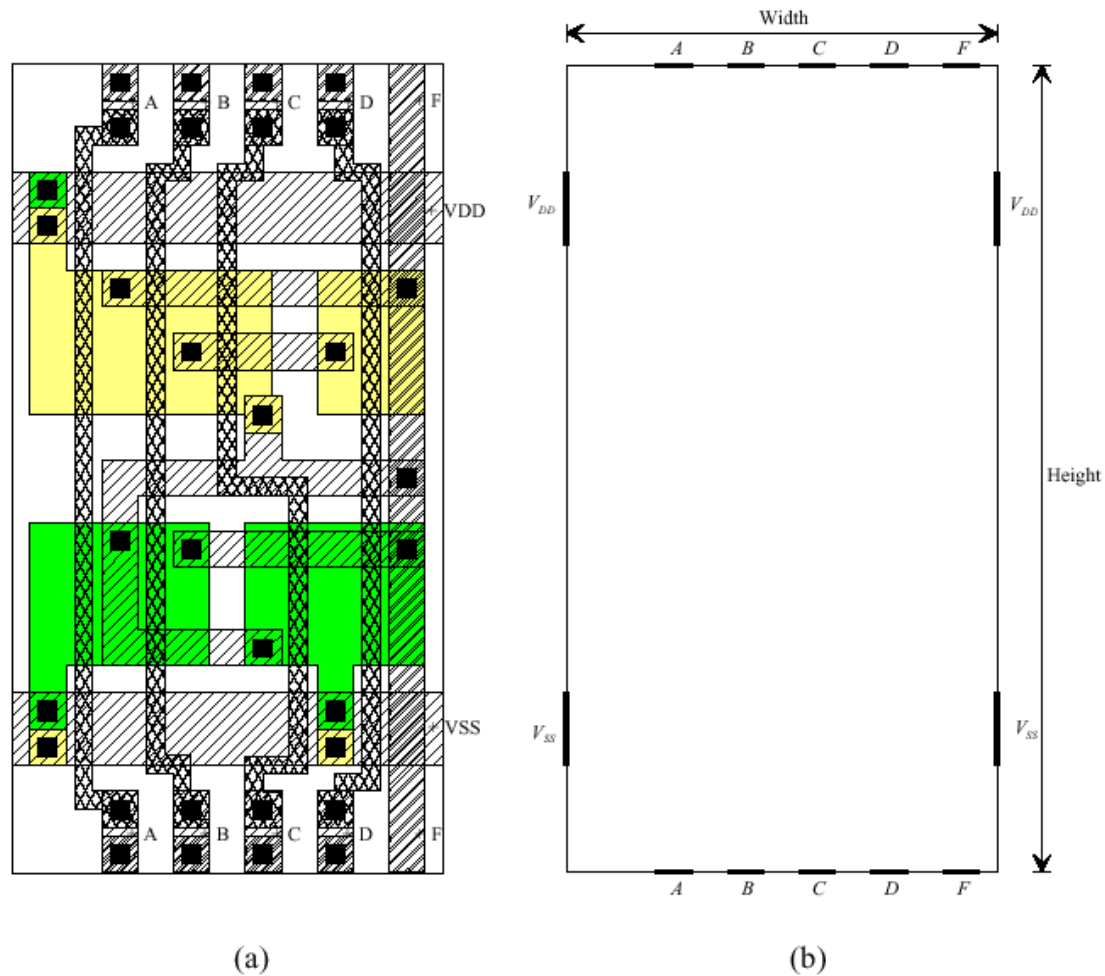


Fig. 1.7 (a) Physical design; (b) Designer's view of a standard cell.

Standard Cell Design

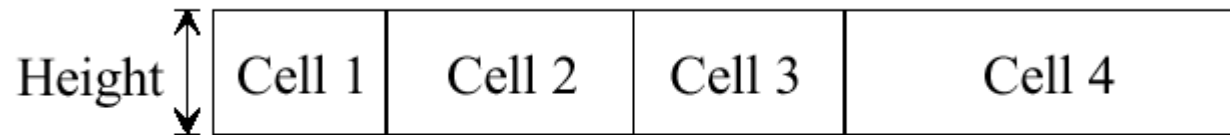


Fig. 1.8 Arrangement of standard-cells in a row.

Standard Cell Design

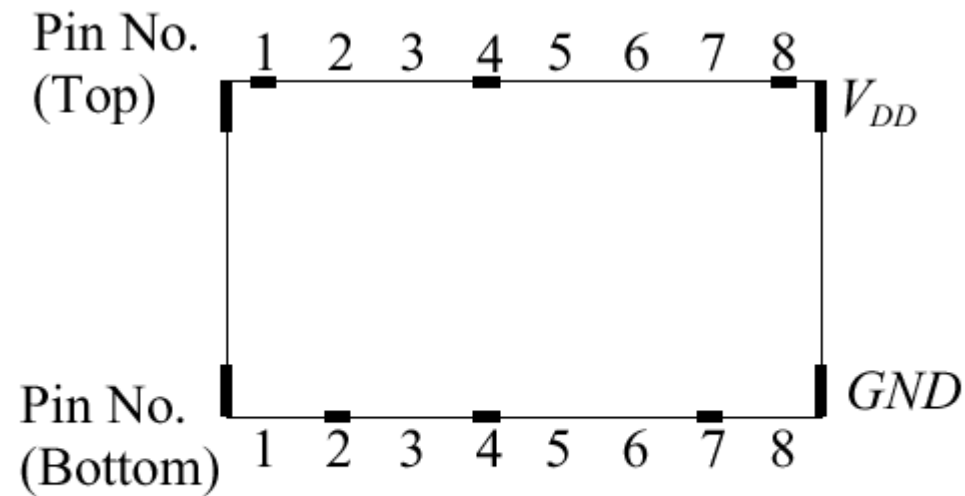
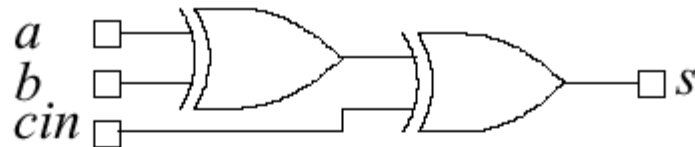


Fig. 1.9 Pin numbers in a standard-cell.

Netlist



```
(a, XOR[1].IN1)
(b, XOR[1].IN2)
(XOR[1].OUT, XOR[2].IN1)
(cin, XOR[2].IN2)
(s, XOR[2].OUT)
(XOR[1].Vdd, XOR[2].Vdd)
(XOR[1].GND, XOR[2].GND)
```

Fig. 1.10 Logic diagram of a circuit and its netlist.

Placement and Routing

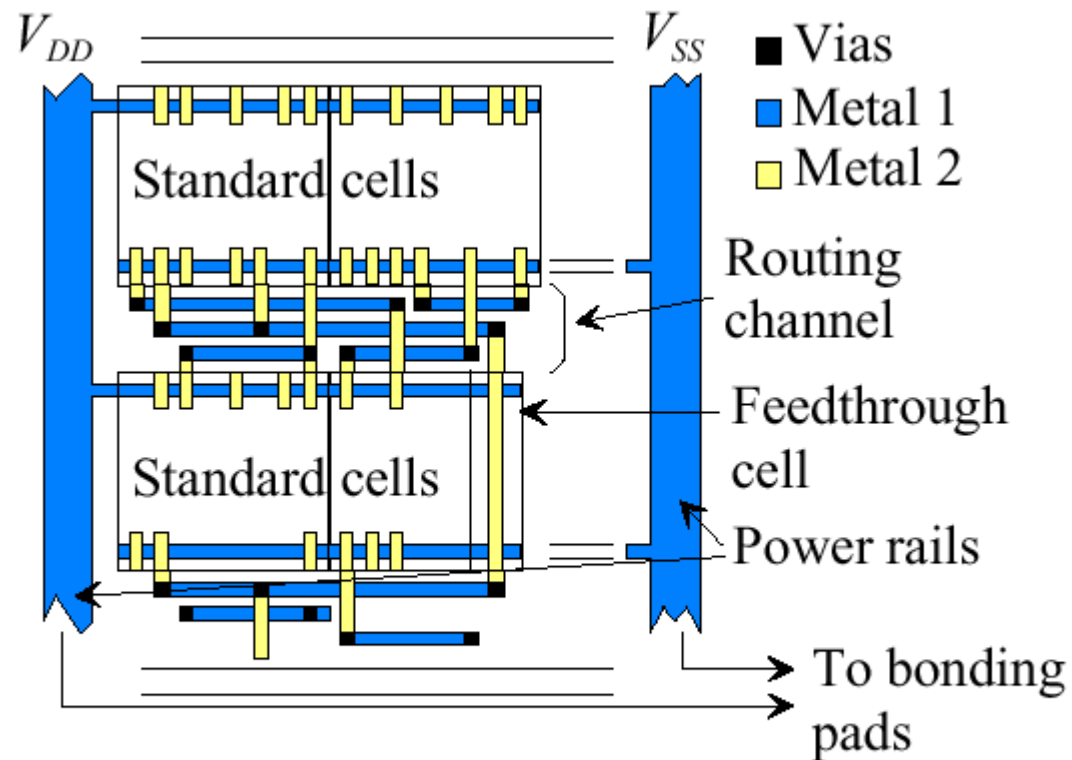


Fig. 1.11 Placement and routing of standard-cells.

Floorplan

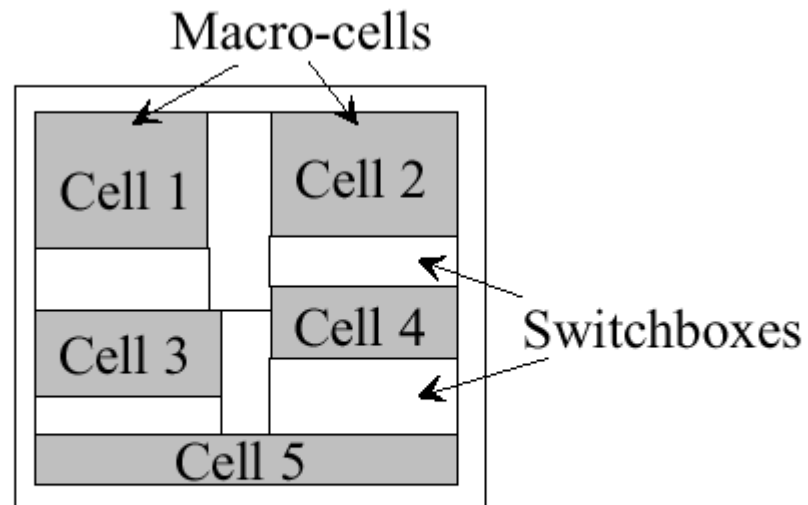


Fig. 1.12 Floorplan of a layout using macro-cells.

Switchbox Routing

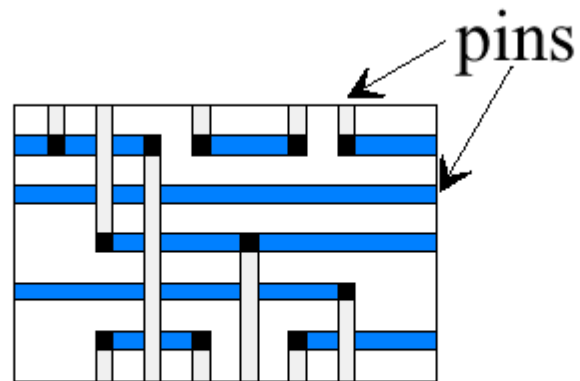


Fig. 1.13 Switchbox routing example.

Fabrication Process

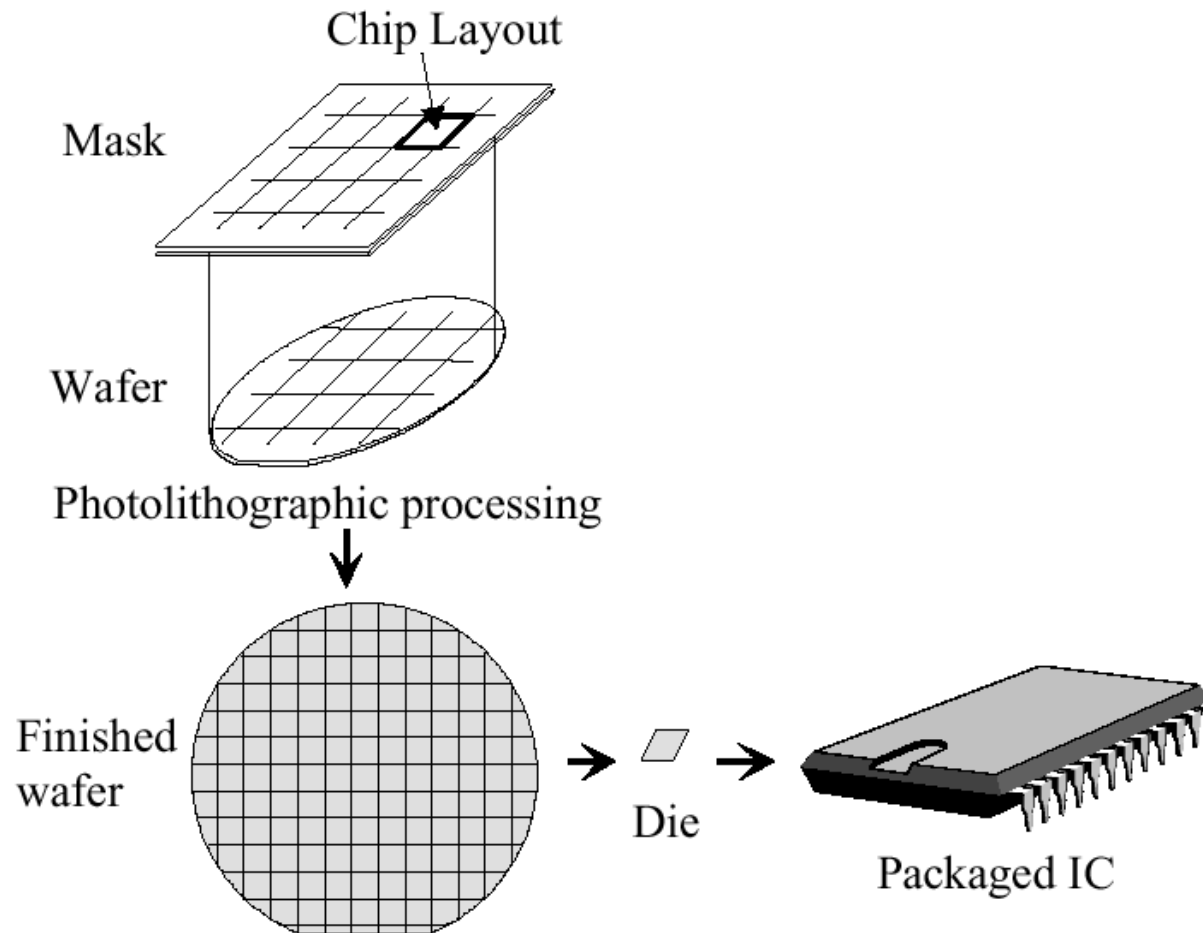


Fig. 1.14 Simplified fabrication process of an integrated circuit.

Mask Programmable Gate Array

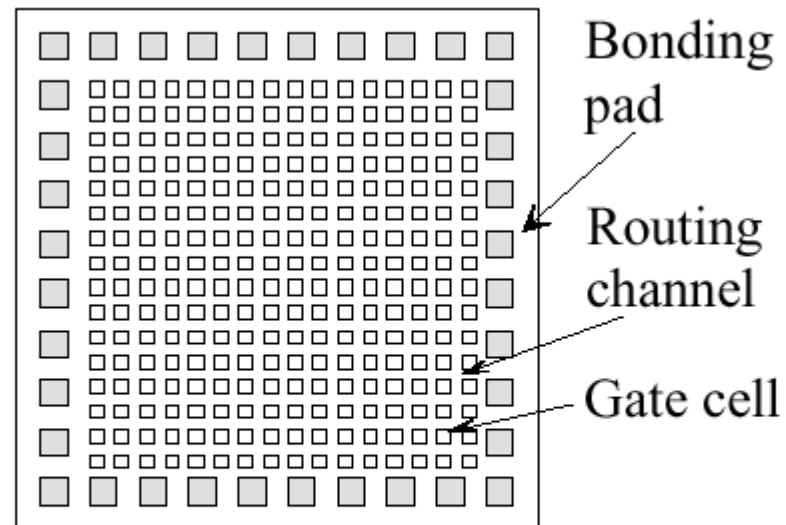


Fig. 1.15 Floorplan of an MPGA.

Gate Array Cell

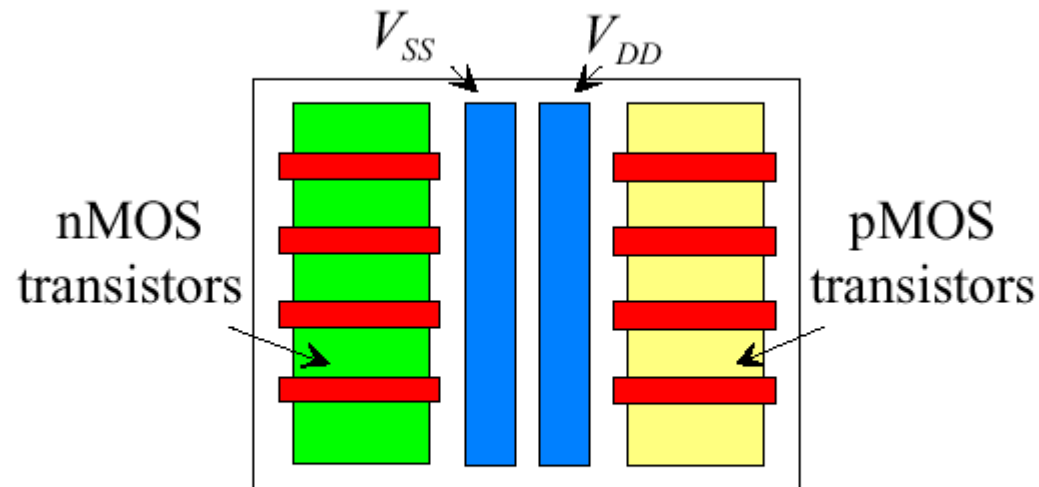


Fig. 1.16 Example of a gate cell in a gate array.

Gate Array Customization

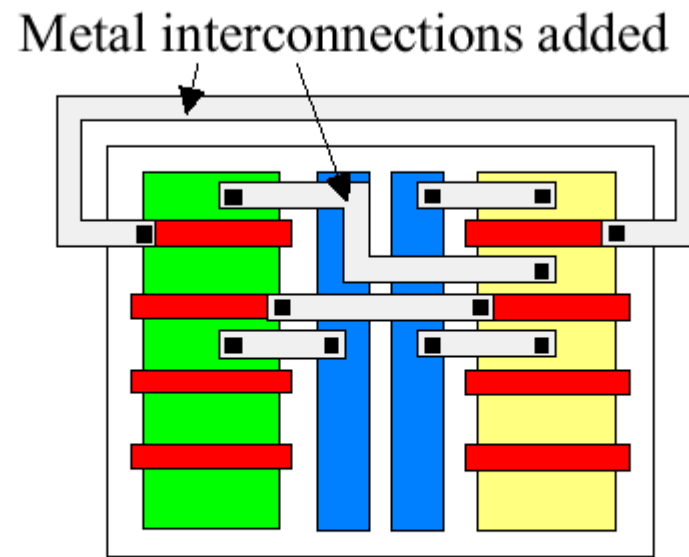


Fig. 1.17 Customization of a gate-cell.

Field Programmable Gate Array

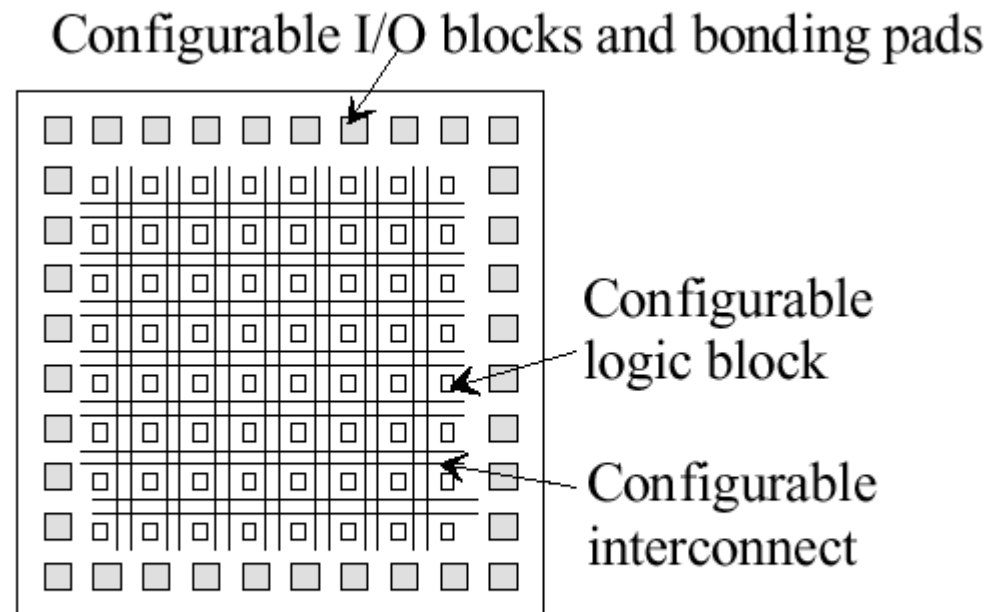


Fig. 1.18 Floorplan of a typical FPGA.

Pad Frame

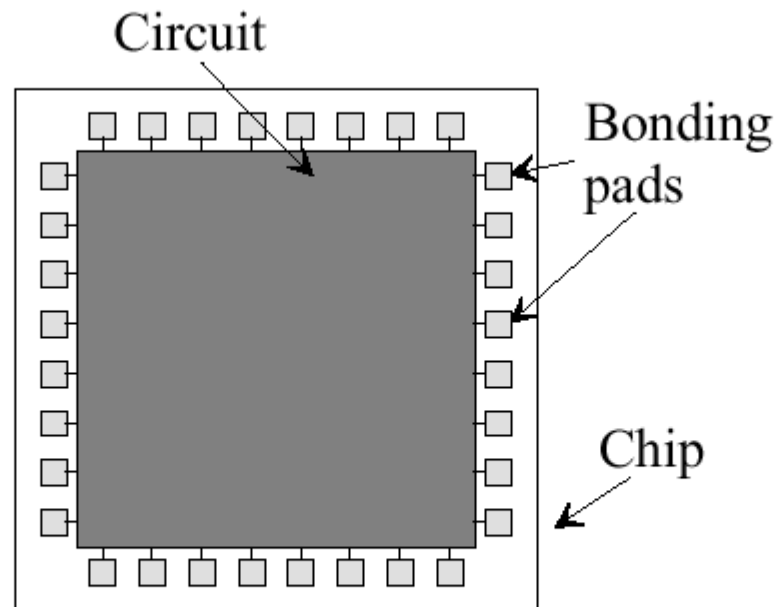


Fig. 1.19 Chip layout including a circuit and a ring of bonding pads (pad frame).

IC Package

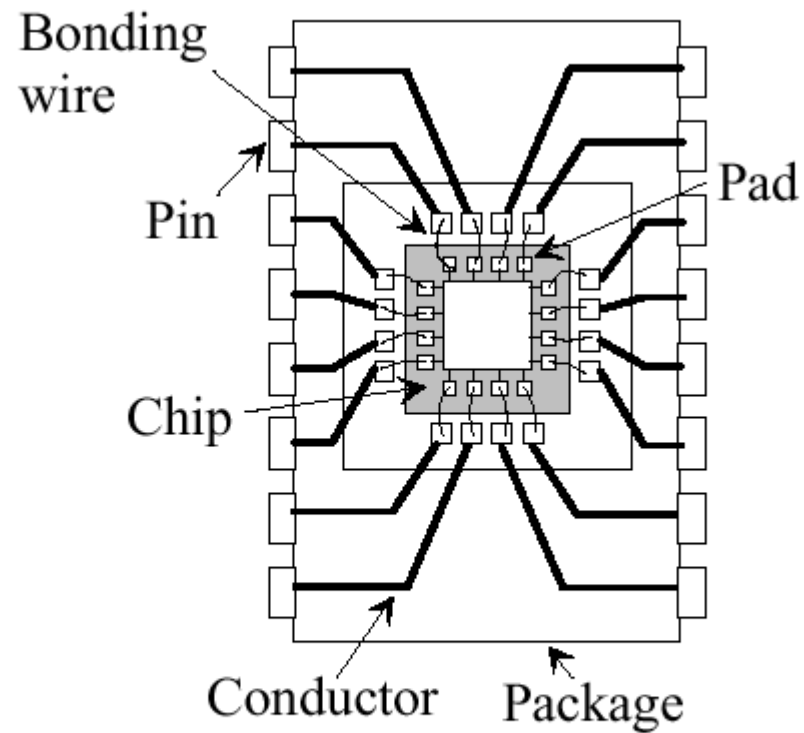


Fig. 1.20 Chip mounted in an IC package.

Pin Grid Array

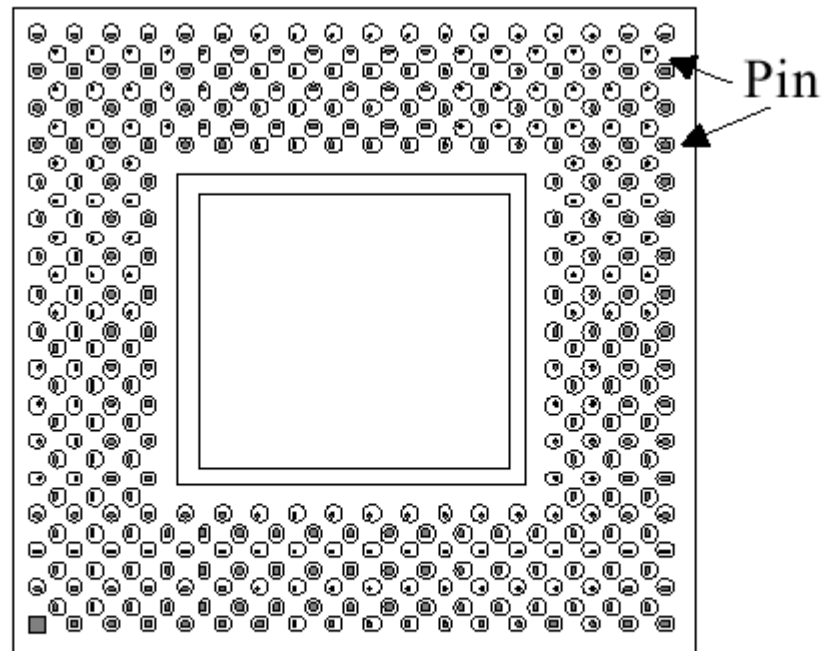


Fig. 1.21 Bottom view of a pin grid array (PGA) package.

Design Flow

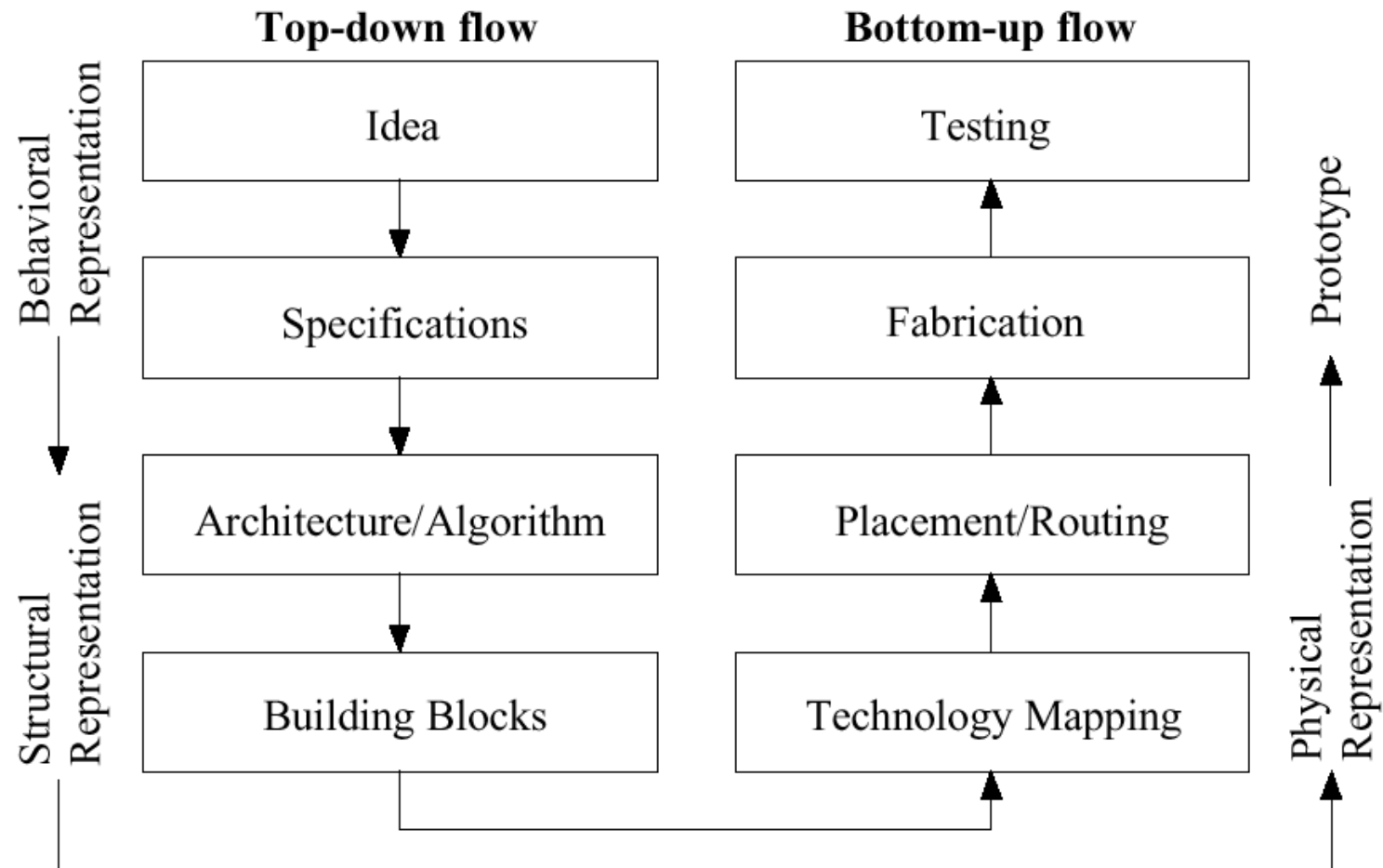


Fig. 1.22 VLSI circuit design flow.